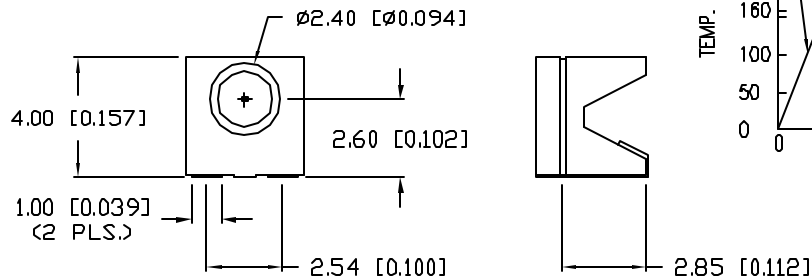
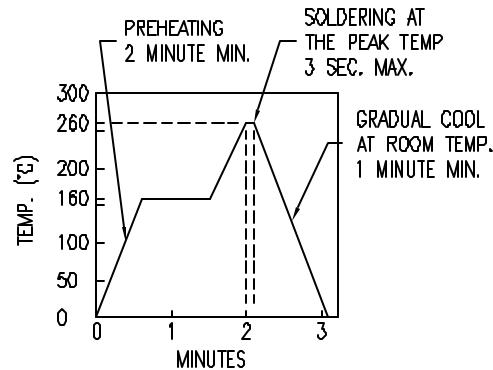
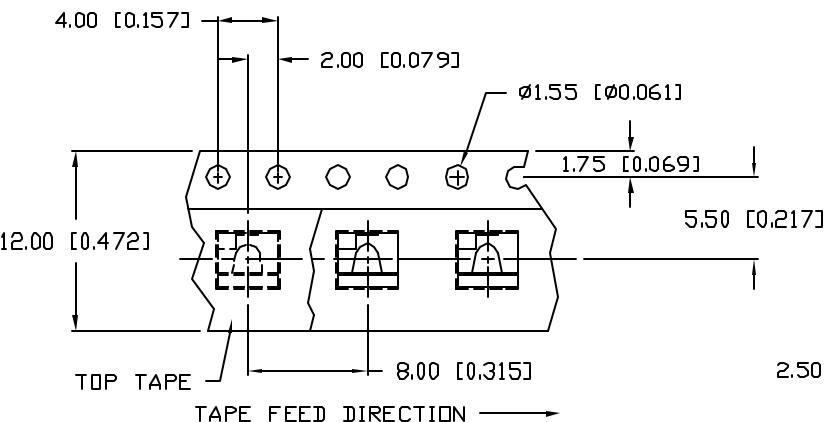


REFLOW PROFILE

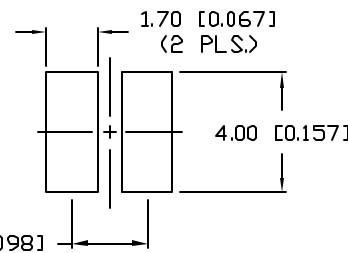


ELECTRO-OPTICAL CHARACTERISTICS $T_A=25^{\circ}\text{C}$ $I_f=20\text{mA}$

| PARAMETER | MIN | TYP | MAX | UNITS | TEST COND |
|--------------------|-------------|-----|-----|----------------|-----------------------|
| PEAK WAVELENGTH | | 525 | | nm | |
| FORWARD VOLTAGE | | 3.5 | 4.0 | V _f | |
| REVERSE VOLTAGE | 5.0 | | | V _r | I _f =100μA |
| AXIAL INTENSITY | | 150 | | mcd | I _f =20mA |
| VIEWING ANGLE | | 120 | | 2x theta | |
| EMITTED COLOR: | GREEN | | | | |
| EPOXY LENS FINISH: | WATER CLEAR | | | | |



RECOMMENDED SOLDER PAD LAYOUT



LIMITS OF SAFE OPERATION AT 25°C

| PARAMETER | MAX | UNITS |
|-----------------------|------------|-------|
| PEAK FORWARD CURRENT* | 130 | mA |
| STEADY CURRENT | 25 | mA |
| POWER DISSIPATION | 105 | mW |
| DERATE FROM 25°C | -1.2 | mW/°C |
| OPERATING TEMP. | -40 TO +85 | °C |
| STORAGE TEMP. | -40 TO +85 | °C |

* t < 10μS

CAUTION: STATIC SENSITIVE DEVICE
FOLLOW PROPER E.S.D. HANDLING PROCEDURES
WHEN WORKING WITH THIS PART.

NOTES:

- 500 PIECES PER REEL.
- THE CATHODE IS ORIENTED TOWARDS THE TAPE SPROCKET HOLE.

*UNLESS OTHERWISE SPECIFIED TOLERANCES PER DECIMAL PRECISION ARE: X=±1 (±0.039), XX=±0.5 (±0.020), XXX=±0.25 (±0.010), XXXX=±0.127 (±0.005), LEAD SIZE=±0.05 (±0.002), LEAD LENGTH=±0.75 (±0.030), MIN.=+DECIMAL PRECISION -0.00, MAX.=+0.00 -DECIMAL PRECISION

REV. PART NUMBER
SML-LXR44UPGC/9-TR

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RIGHT ANGLE BOOMERANG SURFACE MOUNT LED,
525nm ULTRA PURE GREEN LED, WATER CLEAR LENS.

RELIABILITY NOTE
OUR MANY YEARS OF EXPERIENCE DATA ACCUMULATION INDICATE THAT SOLDER HEAT IS A MAJOR CAUSE OF EARLY AND FUTURE FAILURE. PLEASE PAY ATTENTION TO YOUR SOLDERING PROCESS.

DRAWN BY: CHECKED BY: APPROVED BY: DATE: 5.16.05
PAGE: 1 OF 1
SCALE: N/A